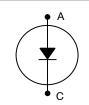
PCRKA30065F8M1

650 V/300 A Extremefast Diode with Solderable Top Metal



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Features

- AEC-Q101 Qualified
- Maximum Junction Temperature 175°C
- Extremefast Technology With Soft Recovery
- Low Forward Voltage (VF = 1.2 V (Typ.) @ IF = 300 A)
- Cathode Pad Covered With Solderable Metal Layer

Applications

- Automotive Traction Modules
- General Power Modules

ORDERING INFORMATION

Part Number	PCRKA30065F8M1				
Packing	Water (sawn on foil)				
	mils	μm			
Die Size	283 × 394	7,200 × 10,000			
Anode Area	243 × 353	6,167 × 8,967			
Die Thickness	3	77			
Top Metal	6 μm AlSiCu + 1.15 μm Ti/NiV/Ag (STM)				
Back Metal	1.4 μm Ti/NiV/Ag				
Topside Passivation	Silicon Nitride plus Polyimide				
Wafer Diameter	200 mm				
Max Possible Die Per Wafer	331				

PCRKA30065F8M1

ABSOLUTE MAXIMUM RATINGS ($T_{VJ} = 25^{\circ}C$ unless otherwise noted)

Parameter	Symbol	Ratings	Units	
Repetitive Peak Reverse Voltage	V_{RRM}	650	V	
DC Forward Current, limited by T _{VJ} max	lF	(Note 1)	Α	
Pulsed Forward Current, tp limited by T _{VJ} max (Note 2)	IFМ	900	Α	
Operating Junction Temperature	T _{VJ}	– 40 to + 175	°C	
Storage Temperature Range	Tstg	+ 17 to + 25	°C	

ELECTRICAL CHARACTERISTICS OF THE DIODE ($T_{VJ} = 25^{\circ}C$ unless otherwise noted)

Parameter	Symbol	Test Condition		Min.	Тур.	Max.	Units
Static Characteristics (Tested	d on wafers)						
Reverse Leakage Current	I _R	V _R = 650 V		_	_	30	μА
Breakdown Voltage	V _{BR}	I _R = 1 mA		650	_	-	V
Forward Voltage	V _F	I _F = 100 A		_	1.1	1.65	V
Electrical Characteristics (No	ot subject to production tes	t – verified by d	esign / characterization)				
Forward Voltage	V _F	I _F = 300 A	T _{VJ} = 25 °C	_	1.2	1.9	V
			T _{VJ} = 175 °C	-	1.1	-	V
Reverse Recovery Charge	Q _{rr}	$I_F = 300 \text{ A}, V_R = 300 \text{ V}$ $dI_F/dt = 3000 \text{ A}/\mu\text{s}, T_{VJ} = 25^{\circ}\text{C}$		-	8.5	-	μC
Reverse Recovery Current	I _{rr}			-	138	-	Α
Reverse Recovery Time	T _{rr}			-	100	-	ns
Reverse Recovery Charge	Q _{rr}			-	9.4	-	μC
Reverse Recovery Current	I _{rr}	$I_F = 300 \text{ A}, V_R = 300 \text{ V}$ $dI_F/dt = 3000 \text{ A}/\mu\text{s}, T_{VJ} = 150^{\circ}\text{C}$			154		Α
Reverse Recovery Time	T _{rr}			-	98	-	nS

^{3.} For ordering, technique and other information on Onsemi automotive bare die products, please contact automotivebaredie@onsemi.com

Depends on the thermal properties of assembly
Not subject to production test – verified by design/characterization

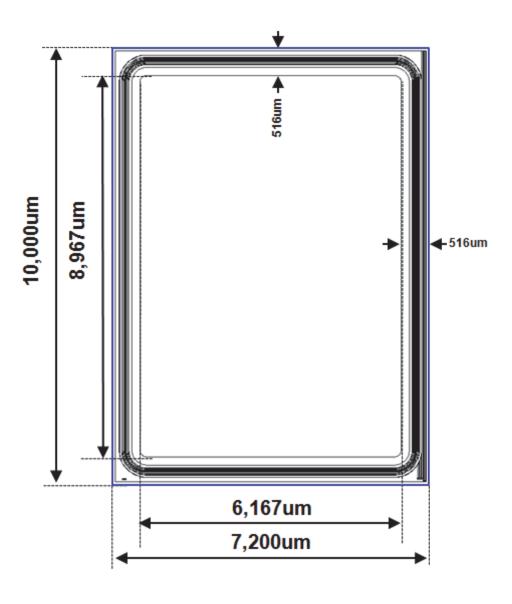


Figure 1. Dimensional Outline and Pad Layout

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